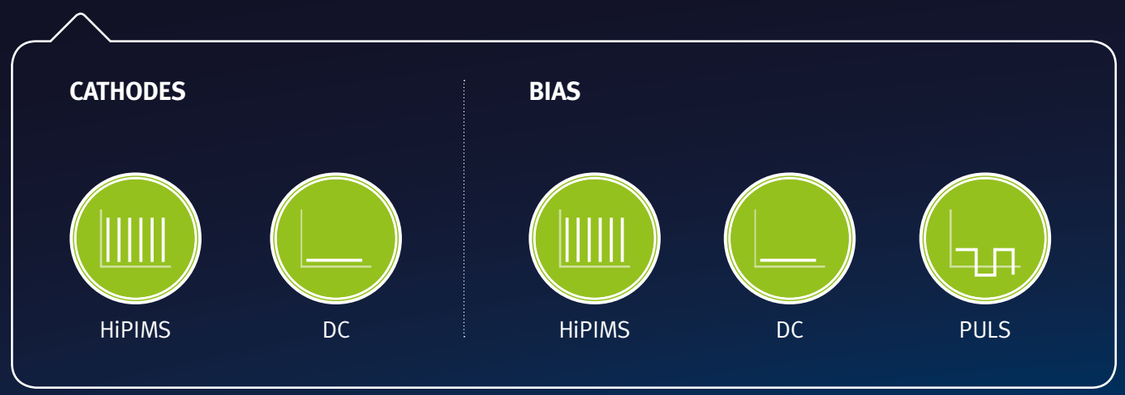
CC800® HiPIMS

HiPIMS HIGH POWER IMPULSE MAGNETRON SPUTTERING



Coating volume, Ø x h	[mm]	Ø400 x 400
Substrate table, Ø x Ø Satellites x number of satellites	[mm], piece	Ø400 x Ø130 x 6
Cathodes	piece, [mm]	6 x 500 (4 of which optionally HiPIMS/DC and 2 further DC; all cathodes are equipped with shutters)
Maximum substrate dimensions, Ø x h	[mm]	Ø400 x 800
Capacity drill, Ø6 mm x 60 mm	piece	1,800
Capacity insert, 12,7 mm x 3,5 mm	piece	4,920
Loading	[kg]	250
Deposition rate	µm/h	2 µm/h in pure HiPIMS
Cycle time for 3 µm FerroCon®*	[h]	4.5
Technologies		HiPIMS and sputtering with booster technology. All established CemeCon coatings are possible.
Substrate pretreatment (plasma etching)		Booster, MF and HiPIMS etching
Electrically conductive coatings		yes
Electrically non-conductive coatings		yes
Electrically non-conductive substrates		yes
Connected load	[kW]	80
Power consumption per batch for 3 µm FerroCon®*	[kWh]	120
External dimensions (w x l x h)	[mm³]	1,450 x 3,350 x 2,200

** pure HiPIMS coatings on 10 mm milling cutter, full load, triple rotation*